Revision: 1.1
Date: 4-Mar-05

Statement of Materials, Construction

LEAD-FREE -- 6L-SC70 -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Alloy 42	0.0029431	Cu	7440-50-8	0.00286952	44.190010	97.5
				Fe	7439-89-6	0.00006916	1.065093	2.35
				Zn	7440-66-6	0.00000324	0.049855	0.11
				P	7723-14-0	0.00000088	0.013597	0.03
				Ag	7440-22-4	0.00000029	0.004532	0.01
2	Die	Silicon Chip	0.0003865	Silicon (Si)	7440-21-3	0.00038	5.92225	99.5
3	Die Attach Material	Conductive Epoxy	0.00005	Epoxy resin	Proprietary	0.0000081	0.12543	15
				Silver (Ag)	7440-22-4	0.00004344	0.66897	80
				Aromatic Amine	Proprietary	0.0000027	0.04181	5
4	Wire	Gold	0.0000502	Gold (Au)	7440-57-5	0.00005	0.7729916	99.99
5	Lead Finish	Tin	0.0002234	Tin (Sn)	7440-31-5	0.00022	3.44031	100
6	Encapsulation	Epoxy Resin	0.0028361	Fused Silica	60676-86-0	0.00208	32.01400	73.3
				Cristalline silica	14808-60-7	0.00011	1.74701	4
				Phenol resin	9003-35-4	0.00028	4.36753	10
				Solid epoxy resin	29690-82-2	0.0002836	4.36753	10
				Brominated epoxy	68928-70-1	0.0000057	0.08735	0.2
				Carbon black	1333-86-4	0.00003	0.43675	1
				Antimony trioxide	1309-64-4	0.00004	0.65513	1.5
Total Package weight			0.00649					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys